



# ULTRA-DENSE MULTI-ROW STRIP

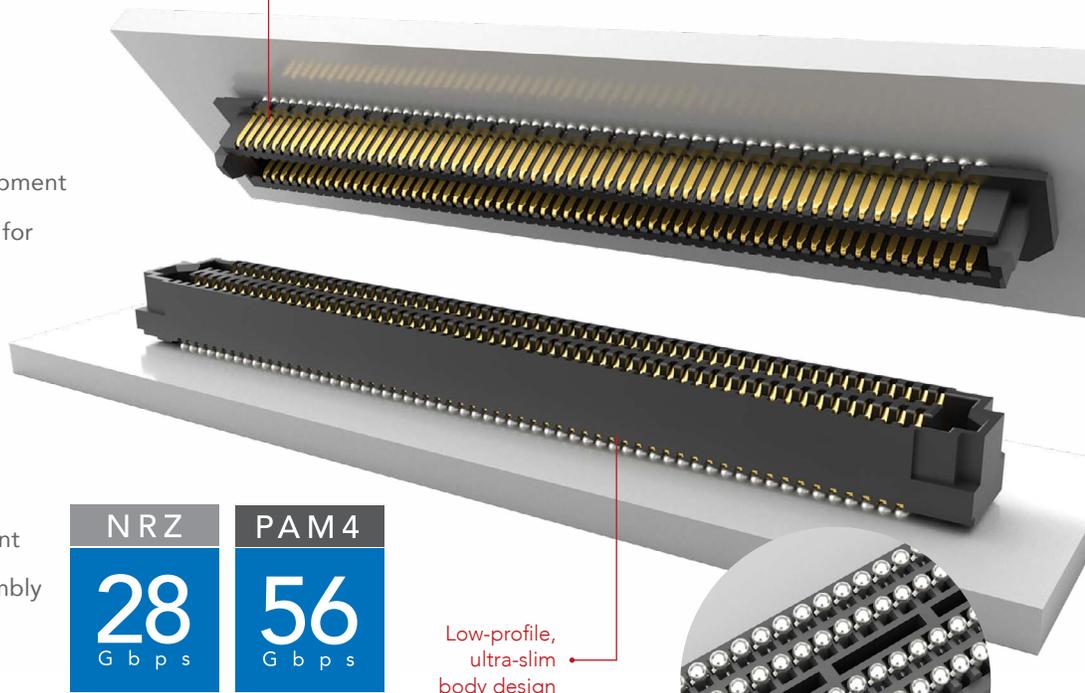
## 0.635 mm PITCH ACCELERATE<sup>®</sup> HD MICRO INTERCONNECTS

### Features & Benefits

- Low-profile 5 mm stack height
- Slim 5 mm width
- Incredibly dense - up to 240 total I/Os
  - 4-row design
  - 10 - 60 positions per row
  - 70 - 100 positions per row in development
- Edge Rate<sup>®</sup> contact system optimized for signal integrity performance
- Open-pin-field design for grounding and routing flexibility
- Supports 56 Gbps PAM4 (28 Gbps NRZ) applications
- PCIe<sup>®</sup> Gen 5 compatible
- 7 - 16 mm stack heights in development
- Roadmap: right-angle and cable assembly

0.635 mm pitch

# ACCELERATE<sup>®</sup> HD

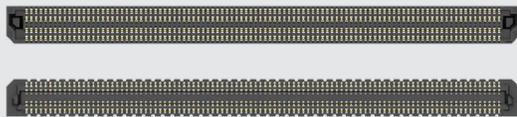


NRZ	PAM4
28	56
Gbps	Gbps

Low-profile, ultra-slim body design

Solder ball technology for simplified processing

### ADM6/ADF6 Series (400 total positions)



68.22 mm x 5.00 mm

### SYSTEM

- ADM6 Series – 0.635 mm Pitch Micro Header
- ADF6 Series – 0.635 mm Pitch Micro Socket

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Please visit [samtec.com/acceleratehd](https://www.samtec.com/acceleratehd) for additional information about AcceleRate<sup>®</sup> HD.